

CLAIMS

1. Electronic device comprising:

- an electronic circuit called active
5 element, comprising a first and a second face, the
first face being provided with electrical connections,
arranged on one side of the circuit only,
- a transfer element, comprising a first
face and a second face and being assembled to the
10 second face of the active element through its first
face, and electrical connections on its second face,
this transfer element being designed to be assembled on
another circuit on the side of this second face,
- at least one wire connection between the
15 electrical connections of the first face of the active
element and the second face of the transfer element.

2. Device according to claim 1, the
transfer element being assembled to the second face of
20 the active element by a layer of glue or a glue film or
a glue strip or soldering means.

3. Device according to claim 1, the
connection being covered by a protection layer.

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4. Device according to claim 1, the
transfer element comprising a ceramic element.

5. Device according to claim 1, the
30 electronic circuit comprising a semiconductor circuit.

6. Device according to claim 5, the electronic circuit comprising a CMOS circuit and / or a CCD circuit and / or an interconnections network, or a bipolar circuit.

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7. Device according to claim 1, the electronic circuit also comprising photon or radiation detection or emission means and / or possibly mechanical or electromechanical means.

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8. Device according to claim 1, comprising a circuit or photon or radiation detection means hybridized onto the first face of the electronic circuit.

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9. Device according to claim 1, also comprising a photon emission circuit or means, hybridized on the first face of the electronic circuit.

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10. Device according to claim 8, the circuits or means hybridized on the first face of the electronic circuit, covering connection means located on this first face.

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11. Device according to claim 1, the second face of the transfer element also comprising connection balls or pins or pads.

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12. Electronic system comprising one or more devices according to claim 11, each transfer element in these devices being connected or fixed to a

common substrate through connection balls or pins or pads.

13. System according to claim 12, each
5 device being separated from its neighbor by a distance of less than 60 μm .

14. Method of manufacturing an electronic device comprising:

10 - the assembly of an electronic circuit called the active element, comprising a first and a second face, the first face being provided with electrical connections, arranged on one side of the circuit, with a transfer element, comprising a first
15 face and a second face and electrical connections on its second face, the assembly being made through its first face to the second face of the active element,

- making a wire connection between the electrical connections of the active element or circuit
20 and the second face of the transfer element.

15. Method according to claim 14, also comprising a protection layer for the wire connection.

25 16. Method according to claim 14, the assembly of the electronic circuit and the transfer element including the formation, of a layer of glue or a glue film or a glue strip or solder means on one and/or the other of the two faces of the electronic
30 circuit and the transfer element to be assembled together.